

LISTING OF THE CLAIMS (1-22)

Claim 1 (Previously amended): A die pad of a leadframe, the die pad having four slots that penetrate the die pad to define a restrictive region having four corners respectively corresponding to the slots such that each slot extends laterally around the corresponding corner substantially outside where the die pad receives a die and such that solder paste for connecting the die to the die pad is substantially restricted to the restrictive region.

Claim 2 (Previously amended): A die pad as in Claim 1 wherein the restrictive region and the die are of approximately identical lateral areas.

Claims 3-4 (cancelled)

Claim 5 (Previously amended): A leadframe comprising a plurality of die pads and a plurality of pins, each die pad having four slots which penetrate that die pad to define a restrictive region having four corners respectively corresponding to the slots such that each slot extends laterally around the corresponding corner substantially outside where that die pad receives a die and such that solder paste for connecting the die to that die pad is substantially restricted to the restrictive region.

Claim 6 (Previously added): A leadframe as in Claim 5 wherein each restrictive region and the die connected to that restrictive region are of approximately identical lateral areas.

Claim 7 (Previously added): A structure comprising:
a die;

a die pad of a leadframe, the die pad having four slots that penetrate the die pad to define a restrictive region having four corners respectively corresponding to the slots, the die connected to the die pad substantially within the restrictive region, each slot extending laterally around the corresponding corner substantially outside where the die pad receives the die; and

solder paste for connecting the die to the die pad such that the solder paste is restricted to the restrictive region.

Claim 8 (Previously added): A structure as in Claim 7 wherein the restrictive region and the die are of approximately identical lateral areas.

Claim 9 (Previously added): A die pad having:

a die location for receiving a die, the die location laterally matching the die and having four corners; and

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a plurality of slots that penetrate the die pad to define a restrictive region such that solder paste for connecting the die to the die pad substantially within the restrictive region is substantially restricted to the restrictive region, one of the slots extending around one of the corners of the die location substantially outside the die location.

Claim 10 (Previously added) A die pad as in Claim 9 wherein another of the slots extends around another of the corners of the die location substantially outside the die location.

Claim 11 (Previously added) A leadframe comprising a plurality of die pads and a plurality of pins, each die pad having:

a die location for receiving a die, the die location laterally matching the die and having four corners; and

a plurality of slots that penetrate that die pad to define a restrictive region such that solder paste for connecting the die to that die pad substantially within the restrictive region is substantially restricted to the restrictive region, one of the slots extending laterally around one of the corners of the die location substantially outside the die location.

Claim 12 (Previously added) A leadframe as in Claim 11 wherein another of the slots in each die pad extends around another of the corners of that die pad's die location substantially outside that die pad's die location.

Claim 13 (Previously added) A structure comprising:

a die;

a die pad having (a) a die location for receiving the die, the die location matching the die and having four corners, and (b) a plurality of slots the penetrate the die pad to define a restrictive region, one of the slots extending laterally around one of the corners of the die location substantially outside the die location; and

solder paste for connecting the die to the die pad substantially within the restrictive region such that the solder paste is substantially restricted to the restrictive region.

Claim 14 (Previously added) A structure as in Claim 13 wherein another of the slots extends around another of the corners of the die location substantially outside the die location.

Claim 15 (Previously added) A structure as in Claim 14 wherein the two corners around which two of the slots respectively extend are adjacent corners of the die location.

Claim 16 (Previously added) A structure as in Claim 14 wherein the two corners around which two of the slots respectively extend are opposite corners of the die location.

Claim 17 (Previously added) A method comprising:

providing a die pad of a leadframe with four slots that penetrate the die pad to define a restrictive region having four corners respectively corresponding to the slots; and providing solder paste between the restrictive region and a die for connecting the die to the die pad such that each slot extends laterally around the corresponding corner substantially outside where the die pad receives the die and such that the solder paste is substantially restricted to the restrictive region.

Claim 18 (Previously added) A method as in Claim 17 wherein the restrictive region and the die are of approximately identical lateral areas.

Claim 19 (Previously added) A method comprising:
providing a die pad with a plurality of slots that penetrate the die pad to define a restrictive region; and
providing solder paste between the restrictive region and a die for connecting the die to the die pad at a die location substantially within the restrictive region such that the die location laterally matches the die and has four corners, such that one of the slots extends laterally around one of the corners of the die location substantially outside the die location, and such that the solder paste is substantially restricted to the restrictive region.

Claim 20 (Previously added) A method as in Claim 19 wherein another of the slots extends around another of the corners of the die location substantially outside the die location.

Claim 21 (Previously added) A method as in Claim 20 wherein the two corners around which two of the slots respectively extend are adjacent corners of the die location.

Claim 22 (Previously added) A method as in Claim 20 wherein the two corners around which two of the slots respectively extend are opposite corners of the die location.